

07-29-2008

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PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Peng GAO, Ching Biing YEO, Xiaobing SUN, Kanzo OKADA

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Sony Corporation
1-7-1 Konan, Minato-ku,
Tokyo, 108-0075, Japan

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): June 16, June 12, June 12 and June 23, 2008.

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

12/154,326 filed May 22, 2008

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: William S. Frommer
Internal Address: Frommer Lawrence & Haug LLP
Street Address: 745 Fifth Avenue
City: New York
State: NY Zip: 10151
Phone Number: (212) 588-0800
Fax Number: (212) 588-0500
E-mail Address: WFrommer@flhlaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account 50-0320
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

- a. Credit Card Last 4 Numbers
Expiration date
b. Deposit Account Number 50-0320
Authorized User Name

9. Signature:

Thomas F. Presson
Signature

July 24, 2008

Date

Thomas F. Presson, Reg. No. 41,442
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 6

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, VA 22311-1450

00568092.DOC

ASSIGNMENT

WHEREAS, I, as below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

AN ULTRASONIC TRANSDUCER ARRAY AND A METHOD FOR MAKING A TRANSDUCER ARRAY

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese Corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

Peng GAO

Name of sole or 1st inventor

Execution date of U.S. Patent Application

X Singapore, Singapore

Residence of sole or 1st inventor

X P. Gao

Signature of sole or 1st inventor

X June 16, 2008

Date of this assignment

Ching Bing YEO

Name of 2nd joint inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of 2nd joint inventor

X

Signature of 2nd joint inventor

X
Date of this assignment

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Peng GAO

Name of sole or 1st inventor

Execution date of U.S. Patent Application

X
Residence of sole or 1st inventorX
Signature of sole or 1st inventorX
Date of this assignment**Ching Biing YEO**

Name of 2nd joint inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of 2nd joint inventor

X
Signature of 2nd joint inventorX
12 Jun 2008
Date of this assignment

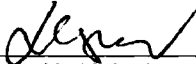
ADDITIONAL INVENTORS**Xiaobing SUN**

Name of 3rd joint inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of 3rd joint inventor

x 

x 12/06/2008

Signature of 3rd joint inventor

Date of this assignment

Kanzo OKADA

Name of 4th joint inventor

Execution date of U.S. Patent Application

Residence of 4th joint inventor

Signature of 4th joint inventor

Date of this assignment

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And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

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Peng GAO	Execution date of U.S. Patent Application
_____ Name of sole or 1st inventor	
_____ Residence of sole or 1st inventor	
_____ Signature of sole or 1st inventor	Date of this assignment
Ching Bliing YEO	Execution date of U.S. Patent Application
_____ Name of 2nd joint inventor	
Singapore, Singapore	
_____ Residence of 2nd joint inventor	
_____ Signature of 2nd joint inventor	Date of this assignment

ADDITIONAL INVENTORS**Xiaobing SUN**

Name of 3rd joint inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of 3rd joint inventor

Signature of 3rd joint inventor

Date of this assignment

Kanzo OKADA

Name of 4th joint inventor

Execution date of U.S. Patent Application

Residence of 4th joint inventor

Signature of 4th joint inventor

Date of this assignment